

Introduction of "QFP Test Socket"

Yokowo Co., Ltd.
7-5-11 Takinogawa,
Kita-Ku Tokyo, Japan
Tel : 03-3916-3111 (Rep.)

■ Summary

Yokowo has developed and launched "QFP Test Socket" in addition to "BGA Test Socket".

■ Background

Regarding to trend of packaged IC, it is clear that production volume of BGA/CSP which is small form factor and higher performance has been increasing day by day; on the other hand, QFP, a traditional package style, which is less cost anticipates a stable demand for consumer application. As of today, leaf spring type test sockets are commonly used for QFP functional testing, however, IC makers or test houses are looking for suitable sockets for narrow pitch devices; pitch size is less than 0.5 mm. In order to respond to the market requirements, Yokowo starts development of test sockets incorporate spring probe contacts.

■ Features

- 1) Guarantee higher operation life cycles; up to 500,000 cycles compare to conventional leaf spring contracts.
- 2) Floating plate feature ensures perfect alignment to the leads.
- 3) Small form factor suitable for multi test sites.
- 4) Double-ended contact probe eliminates soldering process for board assembly.
- 5) Contact probes are replaceable and low cost of ownership.

■ Future Plan

Yokowo enhances marketing activities of this QFP socket for IC markers as well as BGA test sockets. Fabrication of QFP test sockets will be done in Tomioka plant.

Enquiries about this new release to:

CTC Div.

Tel : +81-3-3916-3116